

INSPECT

You are invited!

TRI will showcase the latest 3D SPI and 3D AOI solutions for SEMICON packaging applications at SEMICON Taiwan 2016. Discover highest precision inspection at TRI booth **#982!**

TR7700Q · 3D AOI



- 3D Solder Inspection
- 6 μ m Resolution
- 0250125mm Chip Inspection
- Vacuum Fixture Compatible

TR7007Q · 3D SPI



- Accurate 4-way Fringe Pattern Projection
- 6 μ m Resolution
- High Speed Camera with CoaXPress
- Vacuum Fixture Compatible

